

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1194	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 16:43
L2	1104	257/782	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 16:55
L3	2596	257/784	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 17:13
L4	2556	257/786	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 17:45
L5	2339	438/612	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 18:18
L6	1059	438/666	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 18:40
L7	2271	257/780	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 18:50
L8	3144	257/773	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 19:10

L9	3788	257/774	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 19:31
L10	1098	257/775	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 19:41
L11	1129	257/776	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 19:59
L12	0	257/E21.627	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 19:59
L13	0	257/E21.641	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 19:59
L14	2	257/E29.111	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 19:59
L15	1	257/E29.112	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:00
L16	0	257/E29.113	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:00

L17	1	257/E29.114	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:00
L18	0	257/E29.115	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:00
L19	2	257/E29.116	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:00
L20	6	257/E29.117	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:01
L21	0	257/E29.118	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:01
L22	0	257/E29.119	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:01
L23	0	257/E29.120	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:01
L24	0	257/E29.121	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:01

L25	0	257/E29.122	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:01
L26	1	257/E29.123	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:01
L27	0	257/E29.124	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:01
L28	0	257/E29.125	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:02
L29	0	257/E29.126	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:02
L30	0	257/E29.127	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:02
L31	0	257/E29.128	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:02
L32	16	257/E29.129	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:02

L33	0	257/E29.130	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:10
L34	3	257/E23.015	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:11
L35	0	257/E23.016	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:11
L36	3	257/E23.019	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:11
L37	3	257/E23.02	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:12
L38	9	257/E23.021	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:12
L39	1	257/E23.022	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:12
L40	1	257/E23.023	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:13

L41	2	257/E23.024	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:13
L42	0	257/E23.025	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:13
L43	0	257/E23.026	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 20:13
S1	0	"20030030153"	USPAT	OR	OFF	2005/12/30 15:25
S2	1	"20030030153"	US-PGPUB; USPAT	OR	OFF	2004/07/11 19:32
S3	2	"6018462"	US-PGPUB; USPAT	OR	OFF	2004/07/11 19:34
S4	1	"5519580".PN.	USPAT	OR	OFF	2004/07/11 19:33
S5	1	"6028366".PN.	USPAT	OR	OFF	2004/07/11 19:34
S6	1	"6225573".PN.	USPAT	OR	OFF	2004/07/11 19:34
S7	1	"6246587".PN.	USPAT	OR	OFF	2004/07/11 19:34
S8	1	"6329605".PN.	USPAT	OR	OFF	2004/07/11 19:34
S9	1039147	pad with multi\$4 with (under or lower) layer	US-PGPUB; USPAT	OR	OFF	2004/07/11 19:35
S10	1038997	pad with multi\$4 near (under or lower) layer	US-PGPUB; USPAT	OR	OFF	2004/07/11 19:36
S11	0	pad with multi\$4 near (under or lower) near layers	USPAT	OR	ON	2004/07/11 19:36
S12	33	pad with multi\$4 with (under or lower) near layers	USPAT	OR	ON	2004/07/11 19:49
S13	1598	pad with multi\$4 near layers	USPAT	OR	ON	2004/07/11 20:10
S14	47	(pad with multi\$4 near layers) and 257/781	USPAT	OR	ON	2004/07/11 20:10
S15	9	"5378927"	USPAT	OR	ON	2004/07/11 20:00
S16	203	pad with multi\$4 near layers with (solder or ball or bump)	USPAT	OR	ON	2004/07/11 20:00
S17	145	pad with multi\$4 near layers with (solder)	USPAT	OR	ON	2004/07/11 20:01
S18	26	(pad with multi\$4 near layers) and 257/782	USPAT	OR	ON	2004/07/11 20:12

S19	787	257/782	USPAT	OR	ON	2005/12/23 17:21
S20	1296	257/779	USPAT	OR	ON	2004/07/11 20:51
S21	1108	257/779 and solder	USPAT	OR	ON	2004/07/11 20:52
S22	71	257/779 and solder and pad with (lower or bottom or multi\$4) near (layer or film)	USPAT	OR	ON	2004/07/11 20:57
S23	126	(257/779 or 257/780 or 257/781) and solder and pad with (lower or bottom or multi\$4) near (layer or film)	USPAT	OR	ON	2004/07/11 21:04
S24	1	"4680610".PN.	USPAT	OR	OFF	2004/07/11 20:59
S25	1	"5422516".PN.	USPAT	OR	OFF	2004/07/11 21:00
S26	1	"5442241".PN.	USPAT	OR	OFF	2004/07/11 21:00
S27	1	"5569960".PN.	USPAT	OR	OFF	2004/07/11 21:00
S28	1	"5587341".PN.	USPAT	OR	OFF	2004/07/11 21:00
S29	1	"5731636".PN.	USPAT	OR	OFF	2004/07/11 21:01
S30	1	"5744859".PN.	USPAT	OR	OFF	2004/07/11 21:01
S31	2029	(semiconductor or die or chip or IC) and pad with (lower or bottom or multi\$4) near (layers or films)	USPAT	OR	ON	2004/07/11 21:05
S32	1123	(semiconductor or die or chip or IC) and pad with multi\$4 near (layers or films)	USPAT	OR	ON	2004/07/11 22:05
S33	711	(semiconductor or die or chip or IC) and pad with two near (layers or films)	USPAT	OR	ON	2004/07/11 22:05
S34	3	(semiconductor or die or chip or IC) and pad with two near (lower or bottom) near (layers or films)	USPAT	OR	ON	2004/07/11 22:06
S35	0	(semiconductor or die or chip or IC) and pad with three near (lower or bottom) near (layers or films)	USPAT	OR	ON	2004/07/11 22:06
S36	4	(semiconductor or die or chip or IC) and pad with multi near (lower or bottom) near (layers or films)	USPAT	OR	ON	2004/07/11 22:07
S37	834	(semiconductor or die or chip or IC) and pad with barrier near (layers or films)	USPAT	OR	ON	2004/07/11 22:08
S38	1	"6822329"	USPAT	OR	OFF	2005/02/01 16:21
S39	1	"5736791".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:17
S40	1	"6100589".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:18
S41	1	"6198170".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:18

S42	1	"6297563".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:19
S43	1	"6313540".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:19
S44	1	"6448641".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:20
S45	1	"6313540".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:20
S46	1	"6313540".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:20
S47	24518	(semiconductor or die or chip or IC) and pad with connect\$3	USPAT	OR	OFF	2005/02/01 16:22
S48	1910	257/780	USPAT	OR	OFF	2005/02/03 18:36
S49	1005	257/781	USPAT	OR	OFF	2005/02/01 20:23
S50	2216	257/786	USPAT	OR	OFF	2005/02/02 23:22
S51	746648	"48" not "49"	USPAT	OR	OFF	2005/02/03 18:36
S52	1709	"s48" not "s49"	USPAT	OR	OFF	2005/02/03 18:40
S53	1170	(semiconductor or chip or die) and pad with multi\$4 near layers	USPAT	OR	ON	2005/02/03 19:27
S54	0	"6495917".pn. and bond near structure	USPAT	OR	ON	2005/02/03 19:27
S55	1	"6495917".pn. and pad near structure	USPAT	OR	ON	2005/02/03 19:28
S56	1825	257/779	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 14:58
S57	1136	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 16:21
S58	2	"6495917".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 15:11
S59	1187	257/782	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 16:38

S60	1585	257/779	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/04 23:31
S61	1131	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/04 23:37
S62	1039	257/782	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/04 23:37
S63	29	"5726501"	USPAT	OR	OFF	2005/11/21 12:39
S64	1	"5036383".PN.	USPAT; USOCR	OR	OFF	2005/11/21 12:45
S65	1	"5288661".PN.	USPAT; USOCR	OR	OFF	2005/11/21 12:46
S66	1	"5502337".PN.	USPAT; USOCR	OR	OFF	2005/11/21 12:46
S67	1	"5736791".PN.	USPAT; USOCR	OR	OFF	2005/11/21 12:46
S68	1	"5986346".PN.	USPAT; USOCR	OR	OFF	2005/11/21 12:46
S69	1	"6020647".PN.	USPAT; USOCR	OR	OFF	2005/11/21 12:46
S70	1	"6121160".PN.	USPAT; USOCR	OR	OFF	2005/11/21 12:46
S71	1	"6333558".PN.	USPAT; USOCR	OR	OFF	2005/11/21 12:47
S72	1	"20020005583".PN.	US-PGPUB	OR	OFF	2005/11/21 12:47
S73	1	"6018462".pn.	USPAT	OR	OFF	2005/11/21 13:03
S74	10	"6018462".pn. or "6118180".pn. or "5726501".pn. or "5900643". pn. or "6465895".pn. or "6740945".pn. or "6854633".pn. or "6825541".pn. or "6329605". pn. or "6324754".pn.	USPAT	OR	OFF	2005/11/21 13:03
S75	9	"5721496".pn. or "5859442".pn. or "5918107".pn. or "6424028". pn. or "6597187".pn. or "6621260".pn. or "6770906".pn. or "6852999".pn. or "6952371". pn.	USPAT	OR	OFF	2005/12/23 13:22

S89	4877	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/23 17:21
S90	19	"6191023"	USPAT	OR	OFF	2005/12/27 13:01
S91	1675	257/779	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/30 16:33